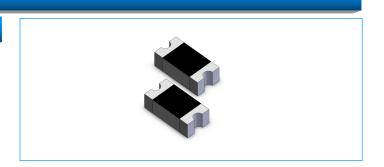




### **SCF0603RZB Series**

#### **Features**

- ♦ RoHS Compliant & Halogen Free
- Faster tripping, 0603 Dimension, Surface mountable, Solid state
- ◆ Operation Current: 0.5A ~ 3.0A
- Maximum Voltage: 6V
- ◆ Operating Temperature: -40 °C ~ +85 °C



#### **Electrical Characteristics**

Part Number	Hold Current	Trip Current	Rated Voltage	Max Current	Typical Power		ım Time Trip	Resis	tance
raitivamisei	I hold (A)	I trip (A)	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	P <sub>dtyp.</sub> (W)	Current (A)	Time (Sec.)	R <sub>min</sub> (Ω)	R <sub>1max</sub> (Ω)
SCF050-0603RZB	0.50	1.00	6.0	50.0	0.5	8.0	0.6	0.070	0.400
SCF075-0603RZB	0.75	1.50	6.0	50.0	0.5	8.0	1.0	0.055	0.250
SCF100-0603RZB	1.00	2.00	6.0	50.0	0.5	8.0	2.0	0.045	0.120
SCF125-0603RZB	1.25	2.50	6.0	50.0	0.5	8.0	3.0	0.035	0.100
SCF150-0603RZB	1.50	3.00	6.0	50.0	0.5	8.0	4.0	0.012	0.080
SCF175-0603RZB	1.75	3.50	6.0	50.0	0.5	8.0	5.0	0.012	0.070
SCF200-0603RZB	2.00	4.00	6.0	50.0	0.5	8.0	5.0	0.012	0.060
SCF260-0603RZB	2.60	5.20	6.0	50.0	0.5	8.0	5.0	0.008	0.050
SCF300-0603RZB	3.00	6.00	6.0	50.0	0.5	8.0	5.0	0.008	0.040

 $I_{hold}$  = Hold Current. Maximum current at which the device will not interrupt in 25  $^{\circ}$ C still air.

Maximum Time-to-trip: Maximum time to trip at assigned current.

 $P_{dtyp}$  = Typical power dissipation: Typical amount of power dissipated from the device when in 25  $^{\circ}$ C still air environment.

 $R_{min}$  = Minimum resistance of device at 25  $^{\circ}$ C prior to tripping.

 $R_{1max}$  = Maximum device resistance is measured one hour post reflow.

#### **Test Procedures and Requirements**

Test Item	Test Conditions	Accept / Reject Criteria
Initial Resistance	In still air at 25˚ℂ	R <sub>min</sub> ≤R≤R <sub>1max</sub>
Time to Ttrip	Specified current, V <sub>max</sub> , 25℃	T≤Maximum Time to Trip
Holding Current	30min, at I <sub>H</sub> , 25℃	No trip
Trip Cycle Life	V <sub>max</sub> , I <sub>max</sub> , 100 cycles	No arcing or burning
Trip Endurance	V <sub>max</sub> , 1 hour	No arcing or burning

I  $_{trip}$  = Trip Current. Minimum current at which the device from low resistance to high resistance in 25  $^{\circ}$ C still air.

*V* <sub>max</sub> = Maximum continuous voltage device can withstand without damage at rated current..

 $I_{max}$  = Maximum fault current device can withstand without damage at rated voltage.





## **SCF0603RZB Series**

## **Physical Characteristics**

Terminal Materials	Tin-Plated Nickle-copper
Soldering Zone	Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.
Moisture Sensitivity	Level 1, per IPC/JEDEC J-STD 020C

### **Environmental Specifications**

Test Item Test Conditions		Resistance Change
Passive Aging	85℃,1000 hours	±10% typical
Humidity Aging	85℃/85%RH.100 hours	±5% typical
Thermal Shock	MIL-STD-202, Method 107G +85℃/-40℃, 20 times	-30% typical
Solvent Resistance	MIL-STD-202, Method 215	No change
Vibration	ML-STD-883C, Test Condition A	No change

## Thermal Derating Chart - I<sub>H</sub> (A)

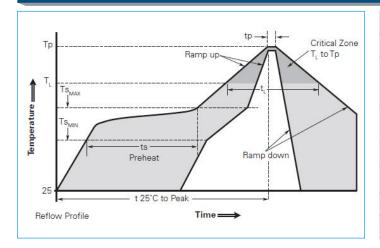
Model	Maximum Ambient Operating Temperature (℃)								
Wodel	-40	-20	0	25	40	50	60	70	85
SCF050-0603RZB	0.66	0.57	0.53	0.50	0.41	0.36	0.34	0.29	0.20
SCF075-0603RZB	0.99	0.86	0.79	0.75	0.62	0.54	0.51	0.43	0.30
SCF100-0603RZB	1.31	1.14	1.06	1.00	0.83	0.71	0.69	0.57	0.40
SCF125-0603RZB	1.64	1.43	1.32	1.25	1.04	0.89	0.86	0.71	0.50
SCF150-0603RZB	1.97	1.71	1.59	1.50	1.24	1.07	1.03	0.86	0.60
SCF175-0603RZB	2.30	2.00	1.85	1.75	1.45	1.25	1.20	1.00	0.70
SCF200-0603RZB	2.63	2.29	2.11	2.00	1.66	1.43	1.37	1.14	0.80
SCF260-0603RZB	3.42	2.97	2.75	2.60	2.15	1.86	1.78	1.49	1.04
SCF300-0603RZB	3.94	3.43	3.17	3.00	2.49	2.14	2.06	1.71	1.20





### **SCF0603RZB Series**

### **Soldering Parameters**



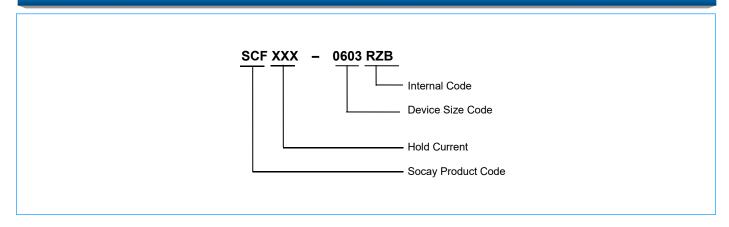
Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T <sub>S</sub> max to T <sub>P</sub> )	3℃/second max.
Preheat: Temperature Min (T <sub>s</sub> min) Temperature Max (T <sub>s</sub> max) Time (T <sub>s</sub> min to T <sub>s</sub> max)	150℃ 200℃ 60-120 seconds
Time maintained above: Temperature(T <sub>L</sub> ) Time (T <sub>L</sub> )	217℃ 60-150 seconds
Peak/Classification Temperature(T <sub>P</sub> )	<b>260</b> ℃
Time within 5 ℃ of actual peak temperature: Time (T <sub>P</sub> )	30 seconds max.
Ramp-down Rate	3℃/ second max.
Time 25℃ to Peak Temperature	8 minutes max.

- Recommended reflow methods: I<sub>R</sub>, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temperature profile meets RoHS leadfree process.

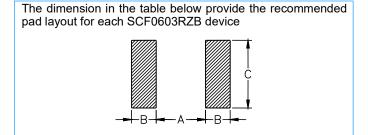
Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperature exceed the recommended profile devices may not meet the performance requirements.

#### **Part Numbering**



## Recommended Solder Pad Layout Dimensions (Unit: mm)



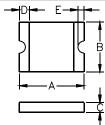
Device	A	В	С	
Device	Nominal	Nominal	Nominal	
0603 Series	0.80	1.00	1.00	





## **SCF0603RZB Series**

### **Product Dimensions (Unit: mm)**



Part Number	A	4	E	3			D	Е
Part Number	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
SCF050-0603RZB	1.45	1.85	0.65	1.05	0.3	0.7	0.15	0.1
SCF075-0603RZB	1.45	1.85	0.65	1.05	0.3	0.7	0.15	0.1
SCF100-0603RZB	1.45	1.85	0.65	1.05	0.4	1.0	0.15	0.1
SCF125-0603RZB	1.45	1.85	0.65	1.05	0.4	1.0	0.15	0.1
SCF150-0603RZB	1.45	1.85	0.65	1.05	0.5	1.2	0.15	0.1
SCF175-0603RZB	1.45	1.85	0.65	1.05	0.5	1.2	0.15	0.1
SCF200-0603RZB	1.45	1.85	0.65	1.05	0.7	1.4	0.15	0.1
SCF260-0603RZB	1.45	1.85	0.65	1.05	0.7	1.4	0.15	0.1
SCF300-0603RZB	1.45	1.85	0.65	1.05	0.7	1.4	0.15	0.1

## **Packaging Quantity**

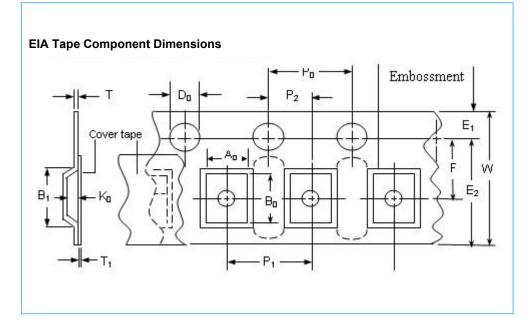
Part Number	Quantity	Part Number	Quantity
SCF050-0603RZB	5000 PCS	SCF175-0603RZB	4000 PCS
SCF075-0603RZB	5000 PCS	SCF200-0603RZB	4000 PCS
SCF100-0603RZB	5000 PCS	SCF260-0603RZB	4000 PCS
SCF125-0603RZB	5000 PCS	SCF300-0603RZB	4000 PCS
SCF150-0603RZB	4000 PCS		



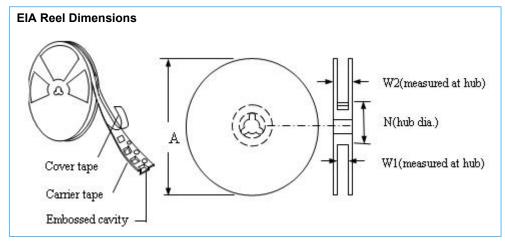


### **SCF0603RZB Series**

### Tape Specifications and Reel Specifications (Unit: mm)



Symbol	Dimensions
W	8.00± 0.10
P <sub>0</sub>	4.0±0.10
<b>P</b> <sub>1</sub>	4.0±0.10
P <sub>2</sub>	2.0±0.05
<b>A</b> <sub>0</sub>	0.95±0.10
Bo	1.85±0.05
D <sub>0</sub>	1.55±0.05
F	3.50±0.05
E <sub>1</sub>	1.75±0.10
Т	0.20±0.02
Leader min.	390
Trailer min.	160



Symbol	Dimensions
Α	178±1.0
N	59±1.0
W1	8.5+1.0/-0.2
W2	12.0±1.0





### SCF0603RZB Series

#### **Warning**



- Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.
- ◆ The electrical resistance and electrical performance specified in the specification are all tested on the test board designated after a reflow soldering. If there is a secondary soldering or other thermal processes, the performance may be attenuated.
- ♦ The holding current of PTC varies at different temperatures, please refer to the specifications and the actual ambient temperature for selection.
- ♦ PTC is designed to protect the occasional overcurrent or overheating failure phenomenon. Long-term or frequent failures will reduce the holding current of the product.
- ◆ The PTC soldering process is reflow soldering. The soldering process can refer to the temperature curve recommended in the specification. Manual soldering of PTC is prohibited. The use of hot air gun soldering of adjacent components will also affect the performance of PTC.
- ♦ PTC is a heat-sensitive component, avoid installing heat source components around it, and avoid installing it in an environment that is compressed or affects its thermal expansion.
- ◆ During installation or use, the PTC is forbidden to be mechanically damaged. It is not recommended to use liquid cleaning products containing organic solvents, which may affect the solder ability of PTC.